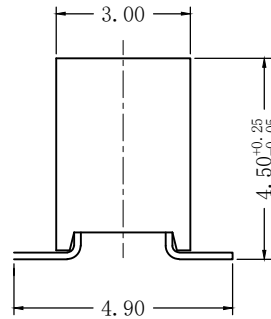
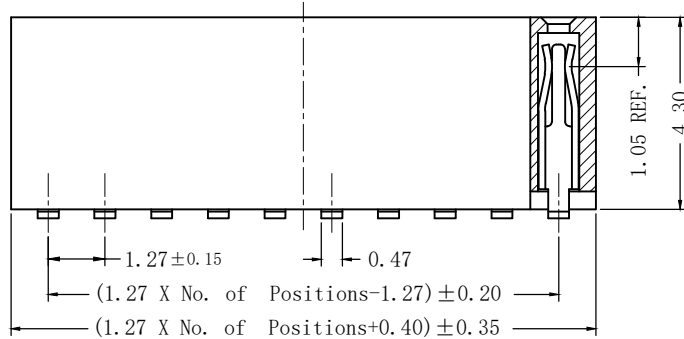
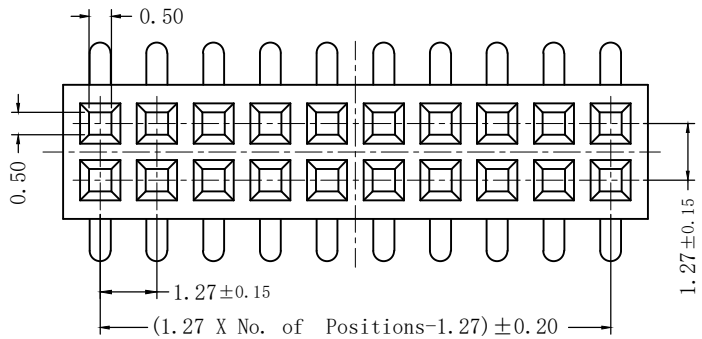


版次	变更内容	审核	日期



技术参数: SPECIFICATIONS

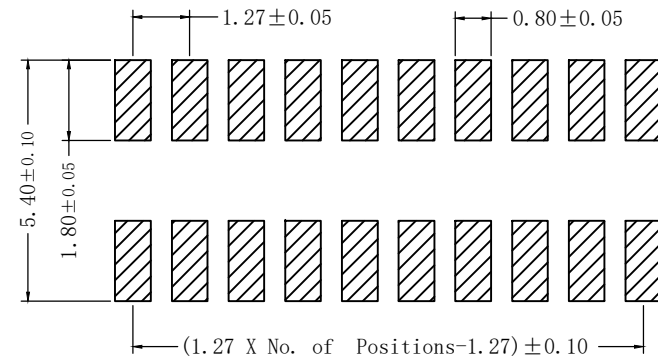
额定电流 (Current Rating): 1A
 绝缘电阻 (Insulation Resistance): 1000MΩ Min.
 接触电阻 (Contact Resistance): 20m Ω Max.
 额定电压 (Dielectric Withstanding Voltage): AC 500V
 工作温度 (Operating Temperature): -40°C ~ +105°C
 最大加工温度 (Max Processing Temp): (230°C for 30~60 seconds)
 (260°C for 10 seconds)
 接触材料 (Contact Material): 磷青铜(Phosphor Bronze), THICKNESS 0.15mm
 塑胶材料 (Insulator Material): 尼龙(Nylon)-9T, UL 94V-0, 颜色: 黑色
 接触电镀 (Contact Plating): 镀金 (Gold plated)
 (电镀规格可根据客户要求来定制)
 Opitonal planting on request.

弯曲度: 2*02P ~ 2*20P 0.30 MAX.
 2*21P ~ 2*35P 0.40 MAX.
 2*36P ~ 2*50P 0.50 MAX.

203-1/B-SMD-3C-2*xxP G-A

单排芯数 01~50P
 塑高 4.3: 4.30mm

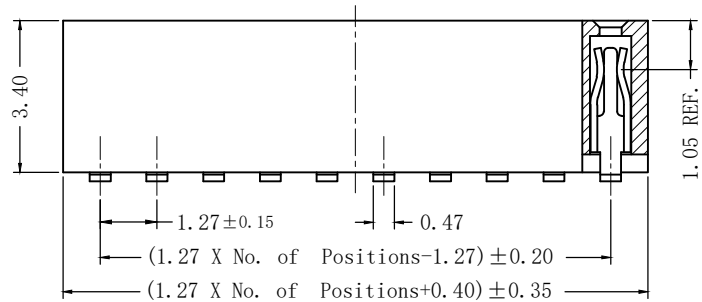
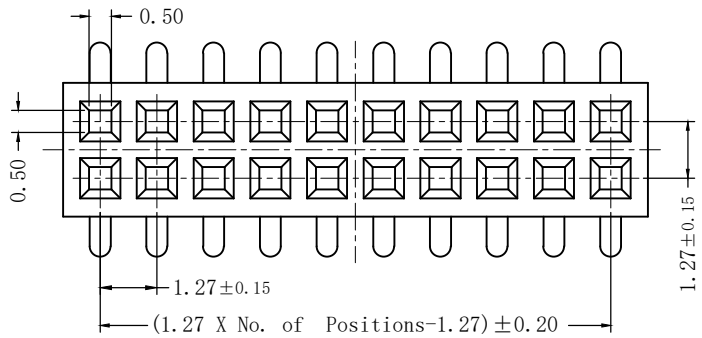
电镀
 G: 镀金Gold Flash
 1G: 镀金1u"
 3G: 镀金3u"
 (镀金可订制)



Recommended PCB Layout

公差:	版次:	A	上海宗进电子科技有限公司		
	比例:		Shanghai Zong Jin Electron Technology Co.LTD		
. X ±0.35	单位:	mm	型号: 203-1/B-SMD-3C-2*xxPG-A	签名	日期
. XX ±0.25	页码:	1/3	描述: 1.27双排贴板排母	绘图:	
. XXX ±2°			图号:	确认:	
LNLB				审核:	

版次	变更内容	审核	日期



弯曲度: 2*02P ~ 2*20P 0.30 MAX.
 2*21P ~ 2*35P 0.40 MAX.
 2*36P ~ 2*50P 0.50 MAX.

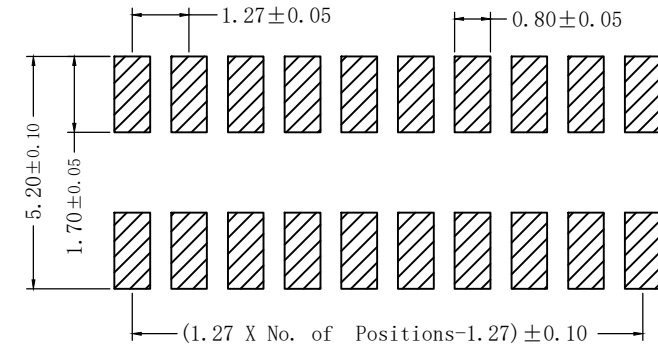
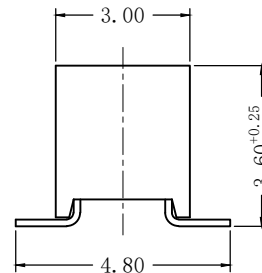
203-1/B-SMD-3C-2*xxP G-A

单排芯数 01~50P
 塑高 3.4: 3.40mm

电镀
 G: 镀金Gold Flash
 1G: 镀金1u"
 3G: 镀金3u"
 (镀金可订制)

技术参数: SPECIFICATIONS

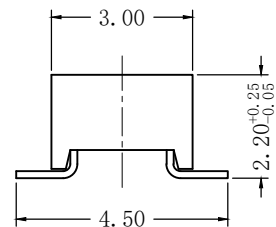
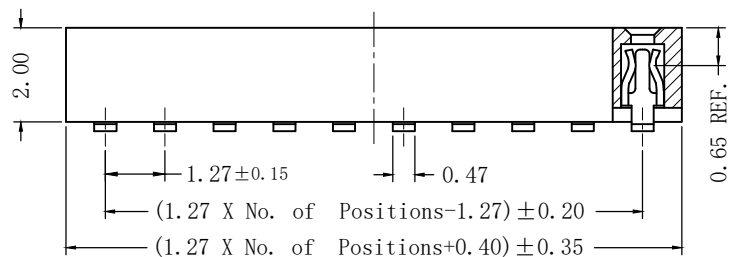
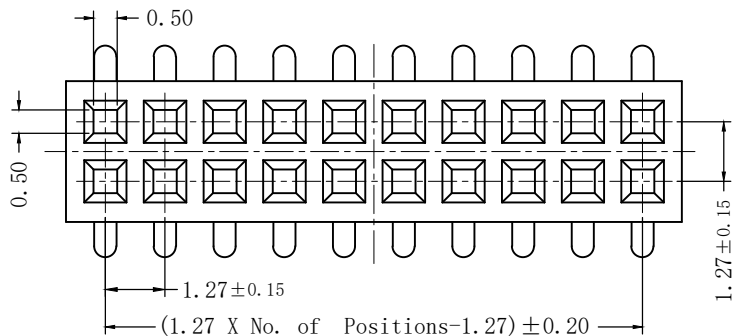
额定电流 (Current Rating): 1A
 绝缘电阻 (Insulation Resistance): 1000MΩ Min.
 接触电阻 (Contact Resistance): 20m Ω Max.
 额定电压 (Dielectric Withstanding Voltage): AC 500V
 工作温度 (Operating Temperature): -40°C ~ +105°C
 最大加工温度 (Max Processing Temp): (230°C for 30~60 seconds)
 (260°C for 10 seconds)
 接触材料 (Contact Material): 磷青铜(Phosphor Bronze), THICKNESS 0.15mm
 塑胶材料 (Insulator Material): 尼龙(Nylon)-9T, UL 94V-0, 颜色: 黑色
 接触电镀 (Contact Plating): 镀金 (Gold plated)
 (电镀规格可根据客户要求来定制)
 Opitonal planting on request.



Recommended PCB Layout

公差: · X ±0.35 · XX ±0.25 · XXX ±2° LNLB	版次:	A	上海宗进电子科技有限公司 Shanghai Zong Jin Electron Technology Co.LTD		
	比例:		型号: 203-1/B-SMD-3C-2*xxPG-A	签名	日期
	单位:	mm	描述: 1.27双排贴板排母	绘图:	
	页码:	2/3	图号:	确认:	
				审核:	

版次	变更内容	审核	日期



技术参数: SPECIFICATIONS

额定电流 (Current Rating): 1A
 绝缘电阻 (Insulation Resistance): 1000MΩ Min.
 接触电阻 (Contact Resistance): 20m Ω Max.
 额定电压 (Dielectric Withstanding Voltage): AC 500V
 工作温度 (Operating Temperature): -40 °C ~ +105 °C
 最大加工温度 (Max Processing Temp): (230 °C for 30~60 seconds)
 (260 °C for 10 seconds)

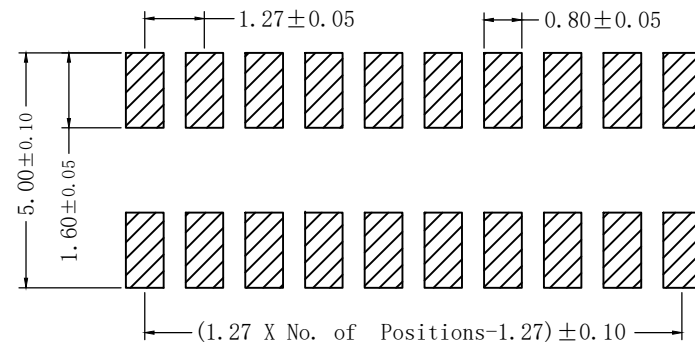
接触材料 (Contact Material): 磷青铜(Phosphor Bronze), THICKNESS 0.15mm
 塑胶材料 (Insulator Material): 尼龙(Nylon)-9T, UL 94V-0, 颜色:黑色
 接触电镀 (Contact Plating): 镀金 (Gold plated)
 (电镀规格可根据客户要求来定制)
 Opitonal planting on request.

弯曲度: 2*02P ~ 2*20P 0.30 MAX.
 2*21P ~ 2*35P 0.40 MAX.
 2*36P ~ 2*50P 0.50 MAX.

203-1/B-SMD-3C-2*xxP G-A

单排芯数 2.0: 2.00mm
 01~50P 塑高

电镀
 G: 镀金Gold Flash
 1G: 镀金1u"
 3G: 镀金3u"
 (镀金可订制)



Recommended PCB Layout

公差:	版次:	A	上海宗进电子科技有限公司		
	比例:		Shanghai Zong Jin Electron Technology Co.LTD		
. X ±0.35	单位:	mm	型号: 203-1/B-SMD-3C-2*xxPG-A	签名	日期
. XX ±0.25	页码:	3/3	描述: 1.27双排贴板排母	绘图:	
. XXX ±2°			图号:	确认:	
LNLB				审核:	